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OMB No. 0651-0011 (exp. 4/94)

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1. Name of conveying party(ies):	2. Name and address of receiving party(ies)
Manfred Schneegans Holger Huebner	Name Siemens Aktiengesellschaft Internal Address: ZT GG VM
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Assignment	Street Address: Postfach 22 16 34
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Execution Date: March 5, 1997	Additional name(s) & address(es) attached? ☐ Yes ☐X No
4. Application number(s) or patent number(s):	
If this document is being filed together with a new application	n, the execution date of the application is:
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08/802,134	
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Name: Lerner and Greenberg	7. Total fee (37 CFR 3.41)\$
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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.	
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**REEL: 9713 FRAME: 0100** 

Docket No.: GR 96 P 1148

## **ASSIGNMENT**

WHEREAS WE. MANFRED SCHNEEGANS and HOLGER HUEBNER, residing respectively at VATERSTETTEN and BALDHAM, Germany, have invented certain new and useful improvements in a

## SEMICONDUCTOR ASSEMBLY WITH SOLDER MATERIAL LAYER AND METHOD FOR SOLDERING THE SEMICONDUCTOR ASSEMBLY

for which an application for Letters Patent of the United States of America was executed on the date of execution of this assignment;

WHEREAS, SIEMENS AKTIENGESELLSCHAFT, a German corporation doing business at München, Germany, is desirous of acquiring the entire interest in said invention, and in any and all Letters Patent of the United States that may be obtained therefor;

NOW, THEREFORE, be it known that for and in consideration of our employment by the said corporation and other valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, we have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said corporation, its legal representatives, successors and assigns, the full and exclusive right to the said invention as fully set forth and described in the above-mentioned application, and to said application and any and all divisions and continuations thereof, and any and all Letters Patent of the United States which may be granted therefor, and any and all reissues of said Letters Patent, the same to be held and enjoyed by the said corporation, its legal representatives, successors and assigns, to the full end of the term for which said Letters Patent may be granted or may be reissued or extended, as fully and entirely as the same would have been held by us had this assignment and sale not been made.

AND WE hereby authorize the Commissioner of Patents to issue any and all Letters Patent of the United States on said invention or resulting from said Application and from any and all divisions and continuations thereof to the said corporation as the assignee of the entire right, title and interest in and to the same.

IN TESTIMONY WHEREOF, we have hereunto set our hands and seals.

In the presence of:

RECORDED: 01/25/1999

PATENT REEL: 9713 FRAME: 0101